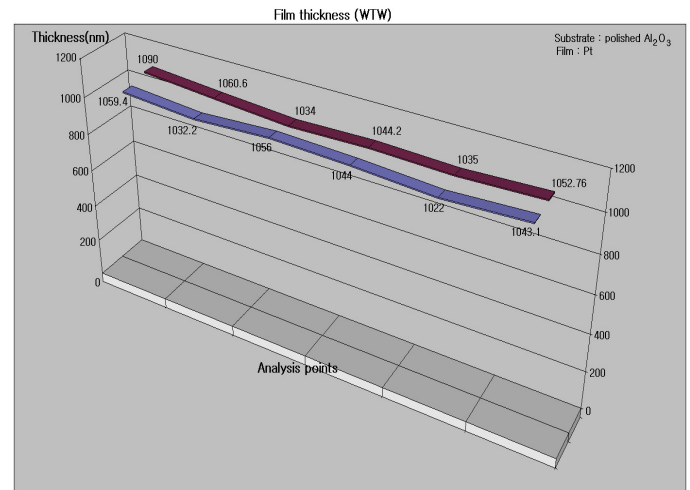


ATS-PVD Series UHV Sputter System for Pt Deposition with 3x8" Guns

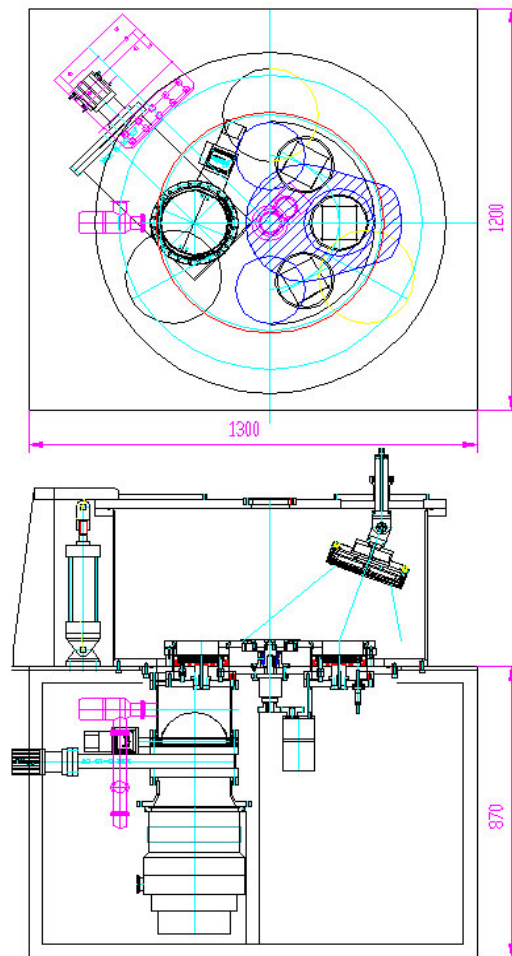


Thickness uniformity of deposited layer
(Deposition rate : 40nm/min @1kW DC)

Special Features

- ◆ UHV sputter system for R&D and small scale production (base pressure: 5×10^{-8} Torr within several hours)
- ◆ Automatical process control
- ◆ Substrate holder with rotational and revolutionary motions
- ◆ Substrate heating up to 500°C
- ◆ Applications
Metalization in various thin film sensors
Other multilayer and codeposition applications
- ◆ Wafer capacity
6 × 4"
- ◆ Average throughput
Up to 11,000 wafers per year
- ◆ Dimension
1300L X 1200H X 1400W (mm³)
- ◆ Others
Power : AC 2.8 kW (13.56MHz) for bias
DC 3kW for Pt sputtering
Gas : Ar / O₂ /N₂
Pump : rotary(980l/min) & turbo(1,500l/s)

◇ Layout



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